



JRC-CERN Collaboration Workshop 27 January 2014, CERN

Material and Surface Characterisation, Materials in Aggressive Environments

- Mandate and expertise of the Materials and Metrology section in the context of the EN-MME group
- Equipment
- Examples of advanced materials and surface characterisation activities and partnerships with industry and laboratories
- Aggressive environments in High Energy Physics (HEP) applications

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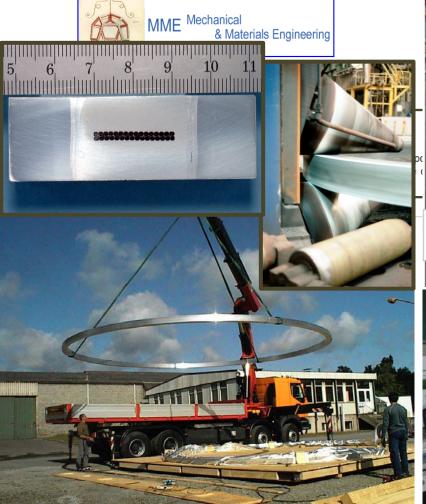
EN Engineering Department

Home > Groups > MME > MM > - Mandate

Metallurgy and Metrology Sec

Undertakes the development, selection, specific control of materials and components including materials and components. Performs allure ana





Mandate

Structure

films. Provides support for the quality chanical tests and measurements on

©CERN 2009



REF N°2

Morphology of a Nb coating on Cu structure, original

200 nm



magnification 50000 x

EHT = 5.00 kV WD = 2.9 mm

HIE-ISOLDE cavity Nb coating on Cu Signal A = InLens Test 43 - Be3 - pt 4
CHAILDEL 190 IIIII X 200 IIIII X 203 IIIIII Test 43 - Be3 - pt 4

Mag = 50.00 K X Maud Scheubel Date :6 Jul 2011



SE and BSE imaging detectors. Max resolution 4 nm Beam 0.5 to 30 kV, 1pA to 500 nA EDS analyser Oxford Isis.

FE-SEM. Zeiss Σigma

Chamber ø365 mm x 275 mm

SE, BSE, in-lens SE imaging detectors. Max resolution 1.5 nm

Beam 0.1 to 30 kV, 4 pA to 20 nA

EDS analysis Oxford Inca with 30 mm² SDD detector

EBSD analysis HKL Chanel 5





n. Observation and analysis



Optical microscopy

Various stereo microscopes.

Metallographic microscope. Leica DMRM

Objectives for magnifications from x16 to x1500

Image analysis system

Digital portable microscope. Keyence VHX-1000

Resolution max 54 MPixel

Objectives 0 - x50, x20 - x200 and x100 - x1000



Spectroscopy and X ray with New optical microscope Zeiss Axio Powder XR diffraction. Siemens 05000

Cu and Cr X-ray sources

Imager purchased in 2013

Vertical and horizontal goniometers

Portable OES analyser. Oxford Instruments PMI MasterPro

Calibrations for steels, Al, Ni, Cu and Ti alloys UV probe for S and P

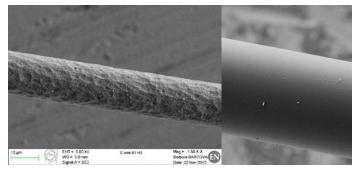
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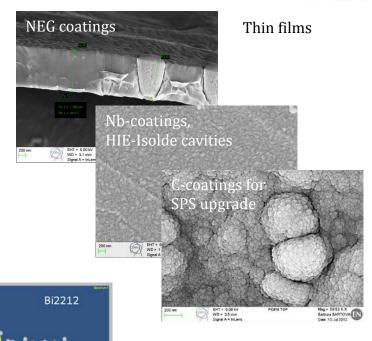


Scanning Electron Microscopy and microanalysis support

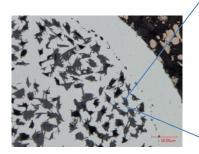


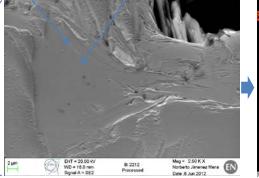
Carbon wires from SPS beam scan: region degraded by the beam (left) and unused reference (right, same scale)



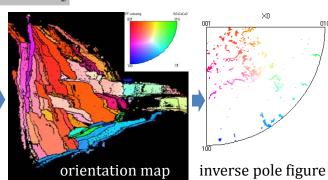


Microstructural characterisation by EBSD of Bi2212 wire





Bi2201





Mechanical testing

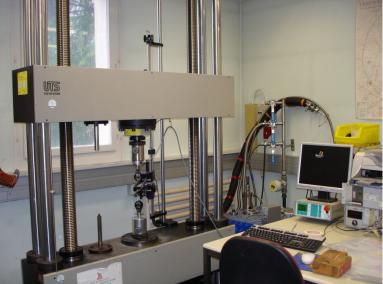
100 kN cryostat for tensile testing and eventually fracture mechanics at 4.2 K in testing and calibration phase terrals &

Tensile testing machines

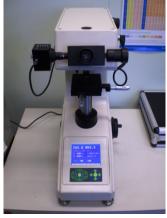
Two column electromechanical universal testing machine *UTS 200*Load cells 1 kN, 20 kN and 200 kN, stroke 800 mm
Knives and clip-on extensometers
Tensile grips, compression plates, bending tools
System for tests at 77 K and 4.2 K, 25 kN load cell
Single column press *ZPM 1000-500*. Load cell 1 kN, stroke 500 mm











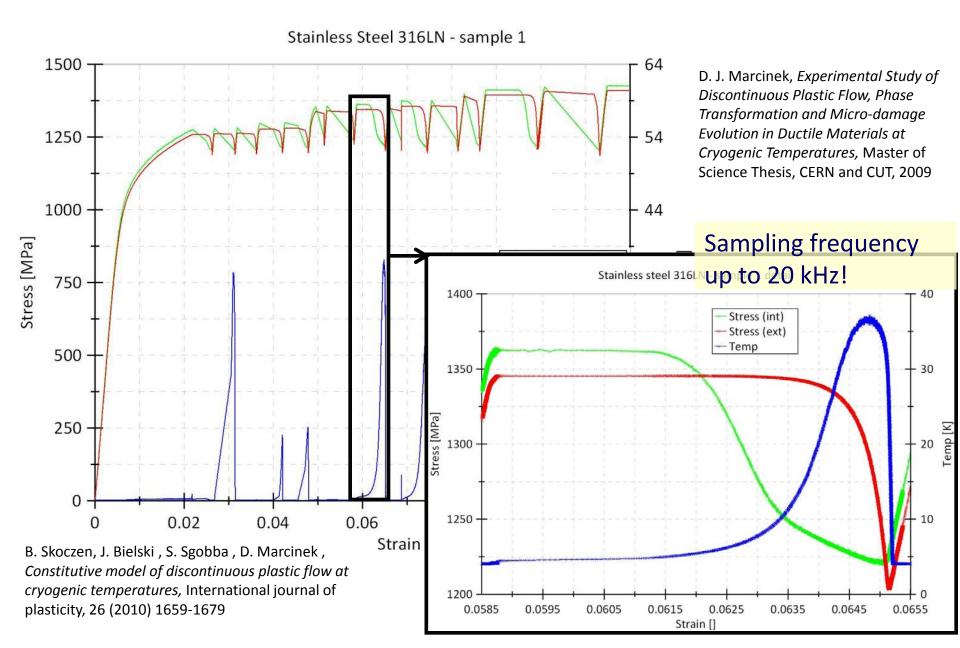
Hardness. Wolpert 2R Load 1 Brinell,

Hardness

Micro hardness autor Load 10



Capabilities of the equipment



5.2 Mechanical Testing

Tensile Strength min, ksi [MPa]

Grade Symbol

150

100

700

800

900

1000

Rp_{0.2} at 4.2 K

The mechanical properties of forgings supplied under this specification shall meet the properties required by ASTM A182, Grade FXM-19.



Elongation in 2 in [50 mm] or 4D,

Area, min. %

Number, HBW

■ HF RT

SF RT

45

30

20

15

10

nº :

934

Nitronic 50

G = 2 + 3

1300

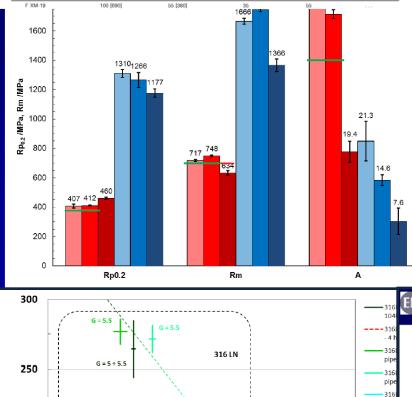
1200

1400

A ×100 25

TABLE 3 Continued

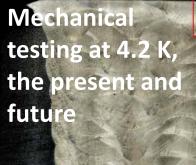
Yield Strength, min, ksi [MPa]⁶



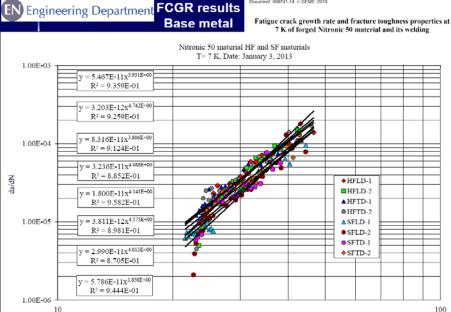
JK2LB

1100





CERN + CEME



ΔK, Mpa √m

Non destructive testing



Visual testing, VT, two level 2 certified

Penetrant testing, PT, two level 2 certified



Ultrasonic testing, UT

Portable flaw detectors. Krautkramer USN 60

Gain 0 dB to 110 dB, probe from 0.25 MHz to 25 MHz,

Portable flaw detector with Phased Array mode. GE Phasor XS

Gain 0 dB to 40 dB, probe from 0.5 MHz to 10 MHz,

Various sectorial or linear transducers

Immersion tank scanner

Scan-surface: 500 mm x 500 mm, 0.1 MHz to 150 MHz

Level 3 and 2 certified operators





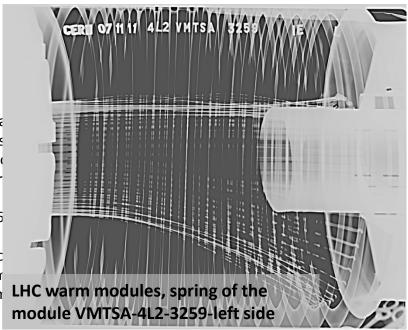


Radiographic testing, RT

Mobile X-ray computed tomogra
Mini-focus x-ray s
Flat panel detector
Software for 3D r
X-ray sources. Philips 160 kV, 0.
Sieffert isovolt 16
Computer radiography system
High definition so
High resolution m
Controlled area (bunker) of 30 n

Level 2 certified operators

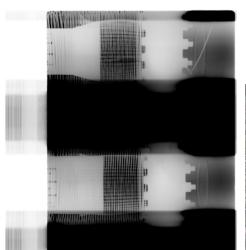




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Non destructive testing

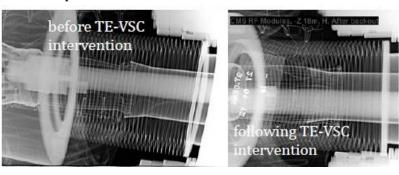




← Computed Radiography Testing (RT) of LSS warm modules. Completion of the radiography campaigns during LHC technical stops. 1767 modules examined, 107 non-conformities identified to be repaired during LS_1, 46 nights.



U Computed RT of CMS RF modules









 \Leftarrow Computed RT of ATLAS RF modules







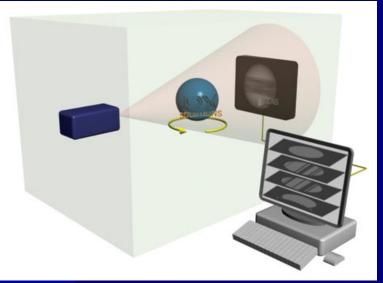
3D tomography







- Specimens placed on a mobile and rotatable stage
- Motorized zoom
- Full inspection of samples up to 240 mm length
- Sealed microfocus source, max. tension 150 kV
- HR area image sensor, 1920 pixels x 1536 pixels
- Detection surface: 200 mm x 250 mm
- 14 bits 16000 gray levels
- 1-30 images /s

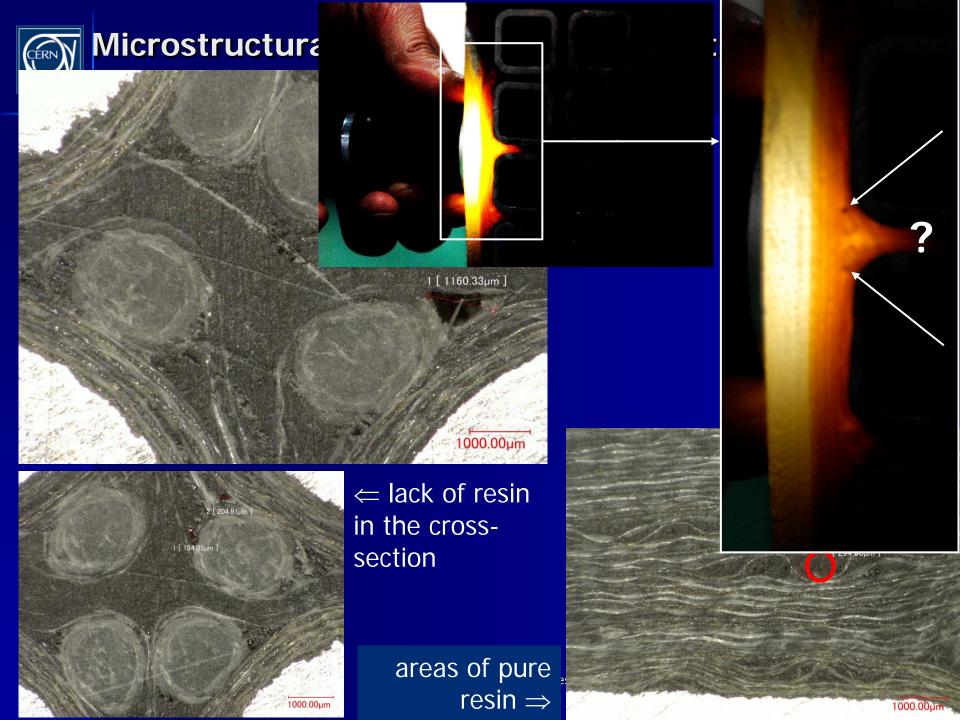


2nd sample of the VPI

11 separate 360° scans were combined to compile a final single 3D object reconstruction while avoiding shadows due to steel conduits



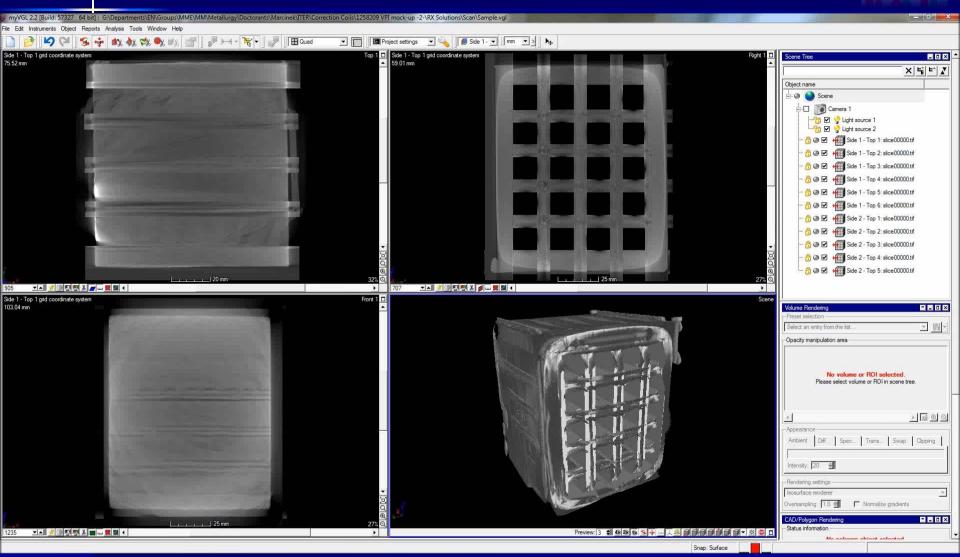






X-Ray Computed Tomography (CT)



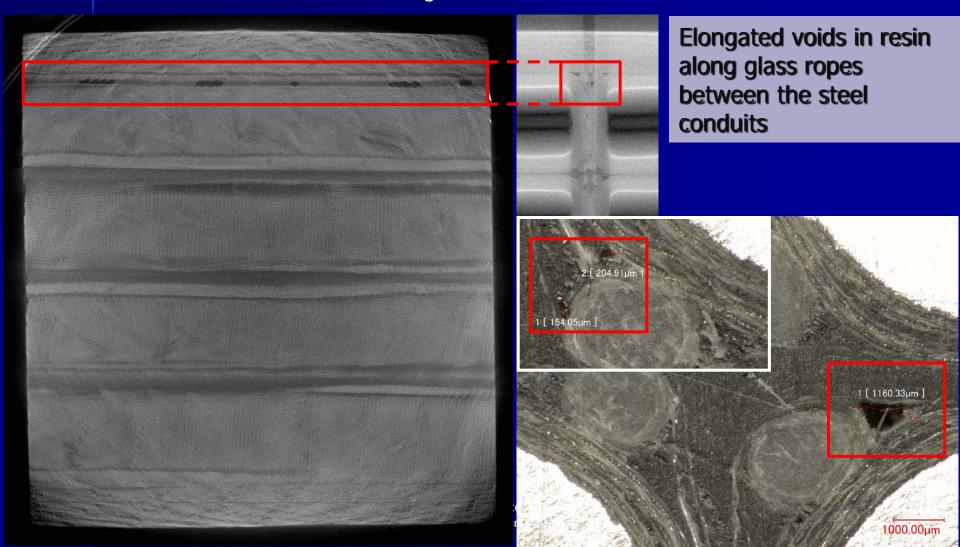


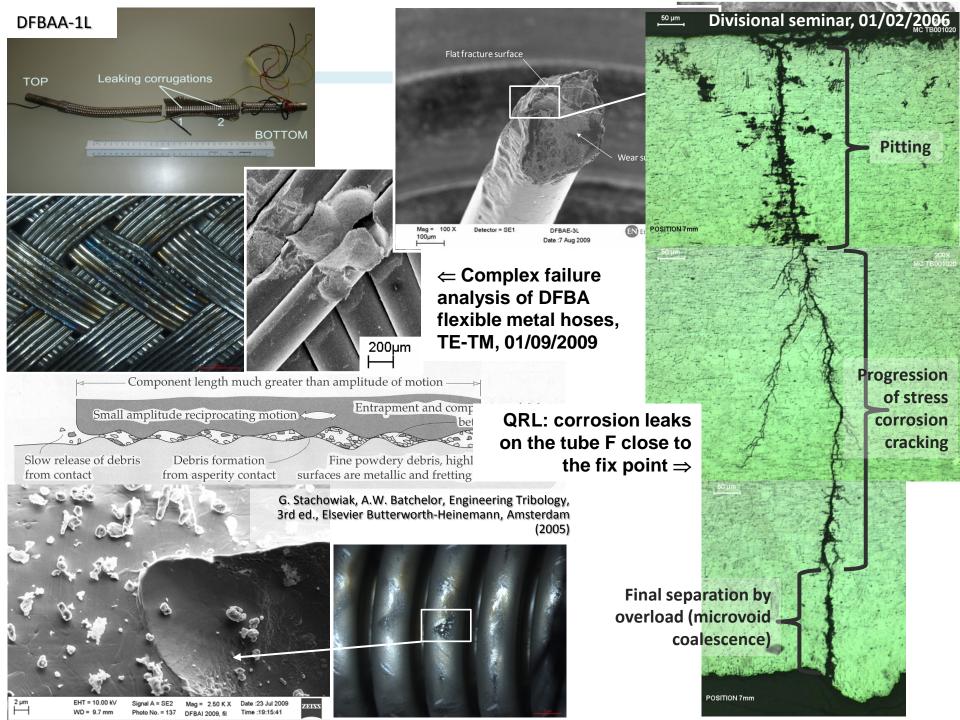


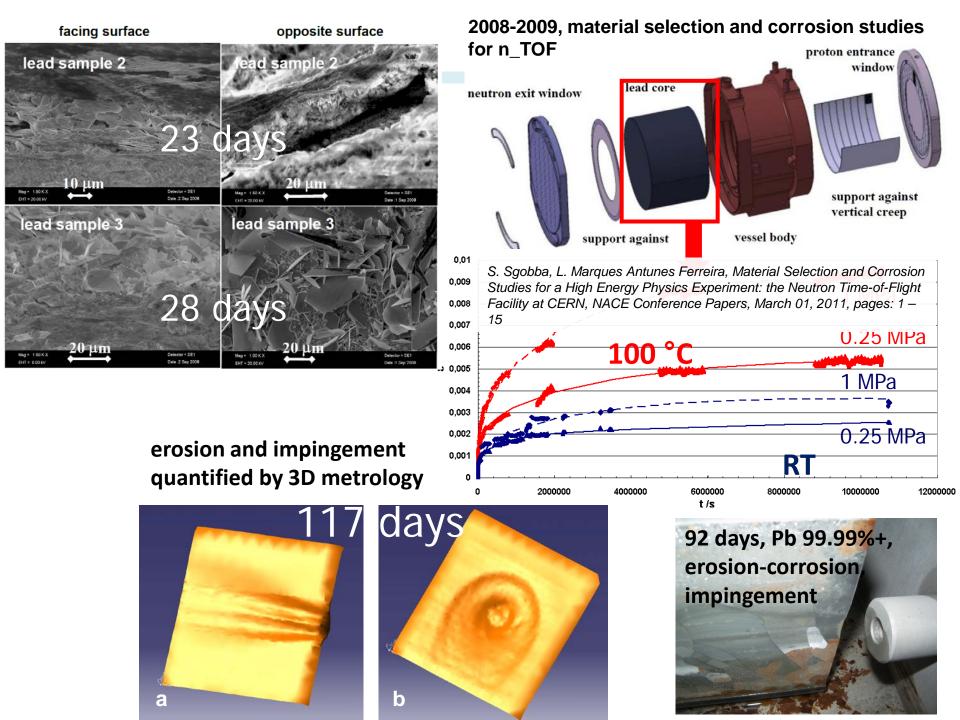
X-Ray Computed Tomography (CT)



Slices extracted from the CT inspection confirming presence of voids along the fibers consistent with metallurgical cross sectional observations











Conclusions

- CERN-wide (and beyond) activity
- Limited but selected and highly specialized equipment
- CERN expertise completed by an extensive network
- Combined resources, facilities and expertise support advanced materials activities at CERN
 - Industrial partners
 - National labs, academy
 - CERN-ITER cooperation agreement (IO, DAs via IO)
- Materials can be submitted to aggressive environments in HEP applications
 - Corrosive environments (radiations, flux residues, erosion, impingement...)
 - Cryogenic temperatures (ductility and fracture toughness to be preserved, response to fatigue, fretting fatigue...)